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(54) **INTELLIGENT LEAK SENSOR SYSTEM FOR DATACENTER COOLING SYSTEMS**

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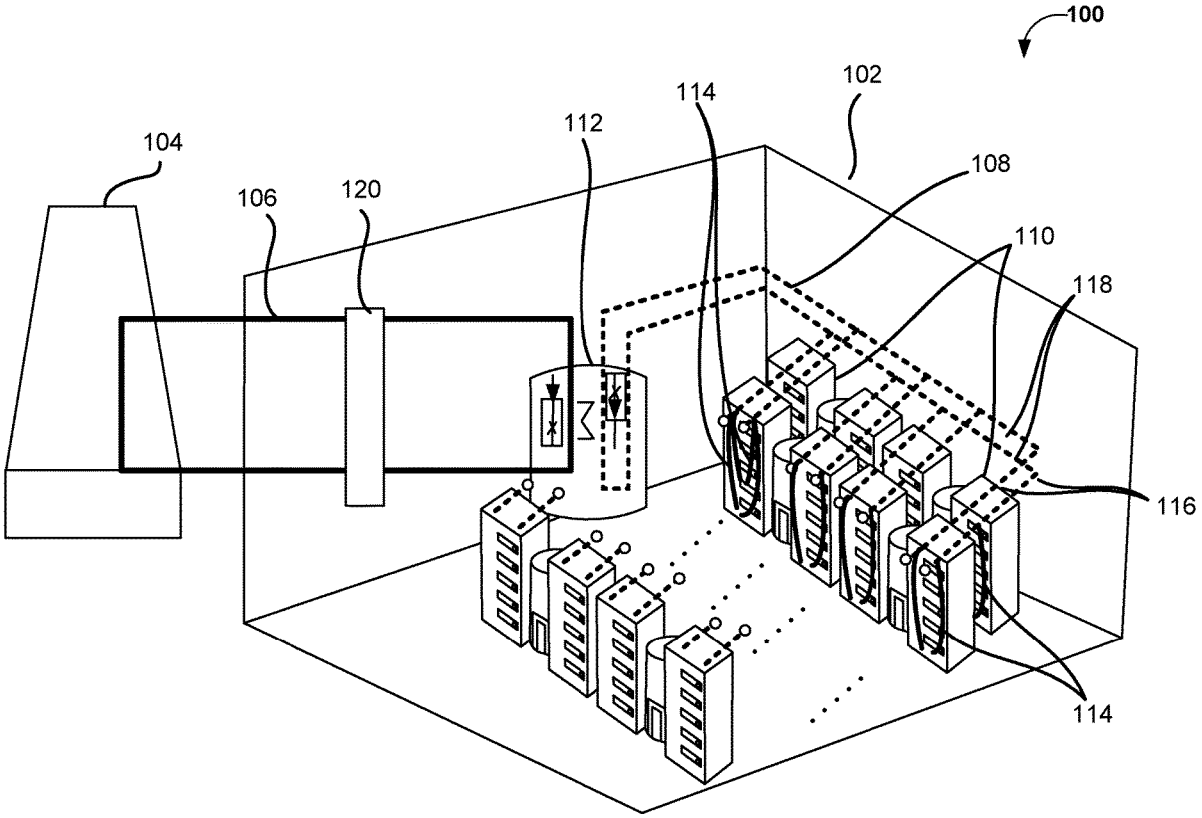
(57) **ABSTRACT**

Systems and methods for cooling a datacenter are disclosed. In at least one embodiment, a sensor string is associated with a first fluid line having a first flow controller and with a second fluid line having a second flow controller, so that sections of such a sensor string are enabled to maintain electrical connectivity there through by a mechanical coupling of a first flow controller and a second flow controller.